



Solid State Equipment Corporation

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FOR IMMEDIATE RELEASE

SSEC Enhances Wafer Bevel and Side Edge Etching

Horsham, PA, June 25, 2007 – Solid State Equipment Corporation announces a new capability for spin etching of SEMI wafer bevel areas. The capability is specifically designed to overcome the challenges of bevel and side edge etching while protecting the wafer active area and enabling independent processing of the backside.

This proprietary tooling is available exclusively on SSEC 3300 etch processors. It enables specific spindle processing of the bevel, independent of the wafer backside. All wet chemistry processes are supported, including final DI water rinsing. The tooling can be used for all wafer sizes, including notched and flat wafers. Benefits include processing of hydrophobic wafers and very low media consumption, for lowest operating cost.

Solid State Equipment Corporation manufactures a full line of single wafer wet cleaners and processors at its headquarters in suburban Philadelphia. SSEC maintains worldwide sales and technical service offices in Horsham, Pennsylvania; San Jose, California; Regensburg, Germany; Cramlington, England; Taiwan, R.O.C.; Shanghai, P.R.C.; Woodlands, Singapore; Gyeonggi, R.O.K.; and Laguna, Philippines.

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